HY510 Grey Thermal Paste

This thermal paste offers high performance and good thermal conductivity ratings. It features a very low contact resistance and creates an ultra-thin bond line. Suitable for CPU and Peltier cooling and other power electronic heat-sink application.

SKU: ASS1159

Brief Specification:

- Item No: HY510.
- Color: Grey.
- Thermal Conductivity: ＞1.93 W/m-k.
- Thermal Impedance: ＜0.225 C-in^2 /W.
- Specific Gravity: ＞2 g/cm^3 .
- Viscosity: 1000.
- Thixotropic Index: 280±10 1/10mm.
- Moment Bore Temperature: -50~300 ℃.
- Operation Temperature: -30~280℃.
- Net Weight: 10g.

Compound:

Ingredients

Silicone Compounds	15	%
Carbon Compounds	35	%
Metal Oxide Compounds	50	%